



SPP2309

P-Channel Enhancement Mode MOSFET

DESCRIPTION

The SPP2309 is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

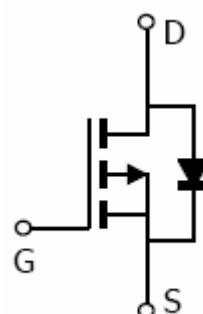
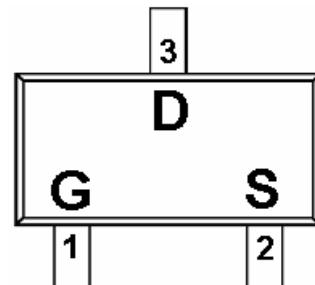
APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

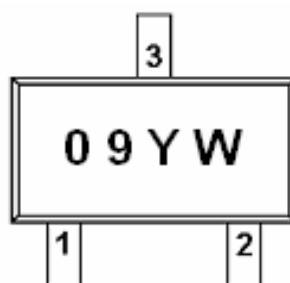
FEATURES

- ◆ P-Channel
 - 20V/2.5A,R_{DS(ON)}= 0.35Ω@V_{GS}=-4.5V
 - 20V/1.5A,R_{DS(ON)}= 0.48Ω@V_{GS}=-2.5V
 - 20V/0.7A,R_{DS(ON)}= 0.75Ω@V_{GS}=-1.8V
- ◆ Super high density cell design for extremely low R_{DS (ON)}
- ◆ Exceptional on-resistance and maximum DC current capability
- ◆ SOT-23-3L package design

PIN CONFIGURATION(SOT-23-3L)



PART MARKING



Y : Year Code
W : Week Code



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PIN DESCRIPTION

Pin	Symbol	Description
1	G	Gate
2	S	Source
3	D	Drain

ORDERING INFORMATION

Part Number	Package	Part Marking
SPP2309S23RG	SOT-23-3L	09YW

※ Week Code : A ~ Z(1 ~ 26) ; a ~ z(27 ~ 52)

※ SPP2309S23RG : Tape Reel ; Pb – Free

ABSOLUT MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	-20	V
Gate –Source Voltage	V _{GSS}	±12	V
Continuous Drain Current(T _J =150°C)	T _A =25°C	ID	-2.5
	T _A =70°C		-1.8
Pulsed Drain Current	I _{DM}	-10	A
Continuous Source Current(Diode Conduction)	I _S	-2.0	A
Power Dissipation	T _A =25°C	P _D	1.25
	T _A =70°C		0.8
Operating Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55/150	°C
Thermal Resistance-Junction to Ambient	R _{θJA}	120	°C/W



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ELECTRICAL CHARACTERISTICS

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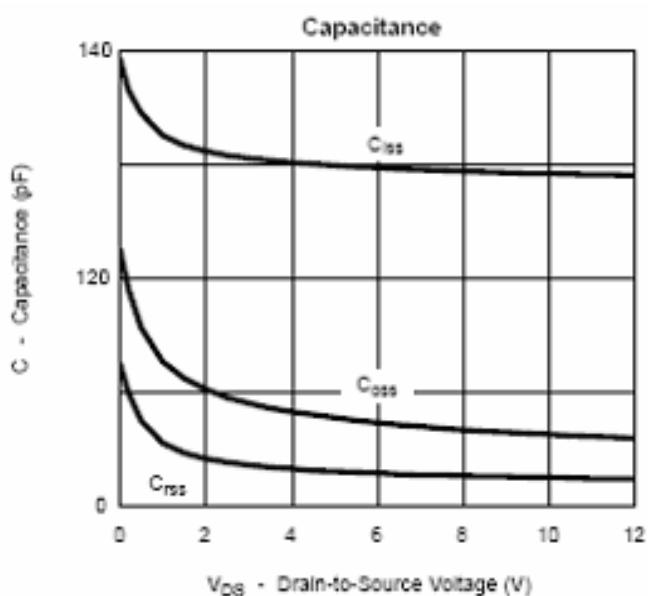
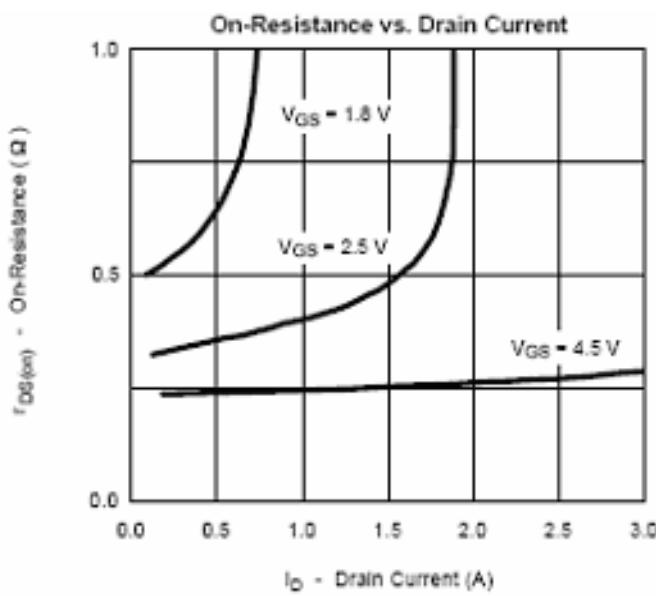
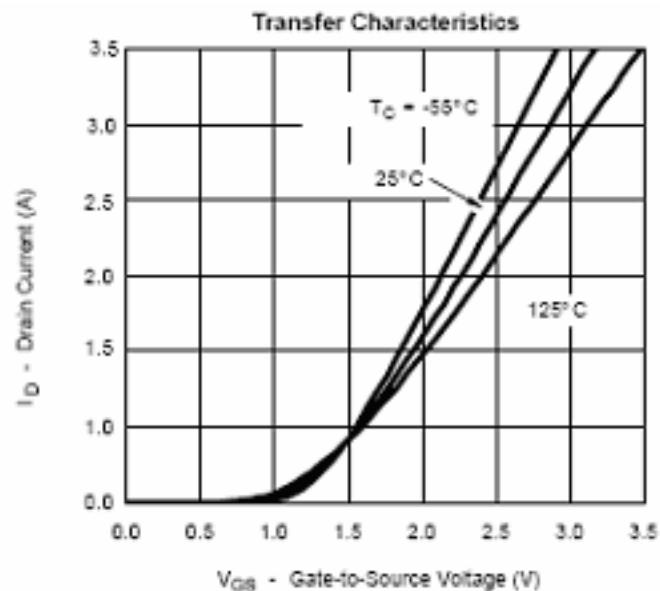
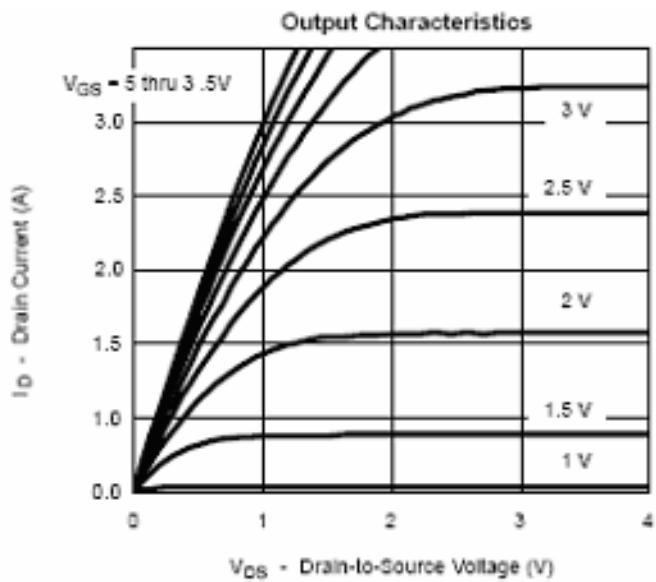
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, ID=-250uA	-20			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , ID=-250uA	-0.35		-0.8	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±12V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-20V, V _{GS} =0V			-1	uA
		V _{DS} =-20V, V _{GS} =0V T _J =55°C			-5	
On-State Drain Current	I _{D(on)}	V _{DS} ≤ -4.5V, V _{GS} =-5V	-2.0			A
Drain-Source On-Resistance	R _{DSS(on)}	V _{GS} =-4.5V, ID=-2.5A		0.29	0.35	Ω
		V _{GS} =-2.5V, ID=-1.5A		0.40	0.48	
		V _{GS} =-1.8V, ID=-0.7A		0.52	0.75	
Forward Transconductance	g _{fs}	V _{DS} =-10V, ID=-1.2A		0.4		S
Diode Forward Voltage	V _{SD}	I _S =-0.5A, V _{GS} =0V		-0.8	-1.2	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =-10V, V _{GS} =-4.5V , ID = -0.7A		1.5	2.0	nC
Gate-Source Charge	Q _{gs}			0.3		
Gate-Drain Charge	Q _{gd}			0.35		
Turn-On Time	t _{d(on)}	V _{DD} =-10V, R _L =10Ω , ID= -1.0A V _{GEN} =-4.5V , R _G =6Ω		5	10	ns
	t _r			15	25	
Turn-Off Time	t _{d(off)}			8	15	
	t _f			1.4	1.8	



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TYPICAL CHARACTERISTICS

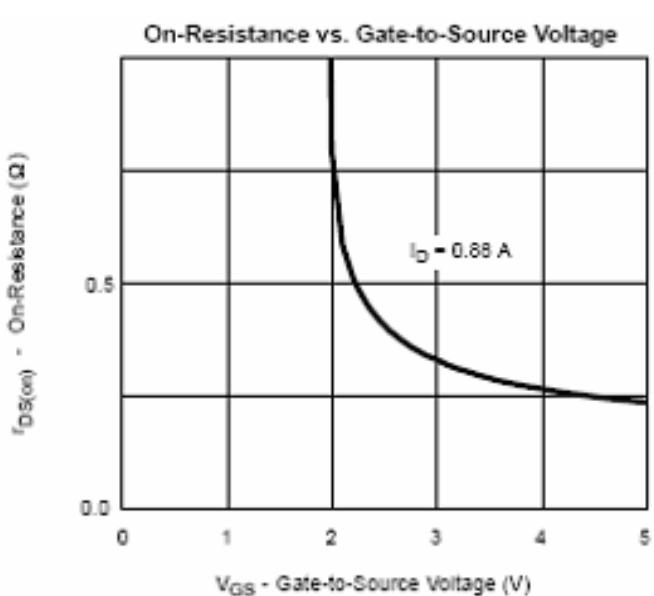
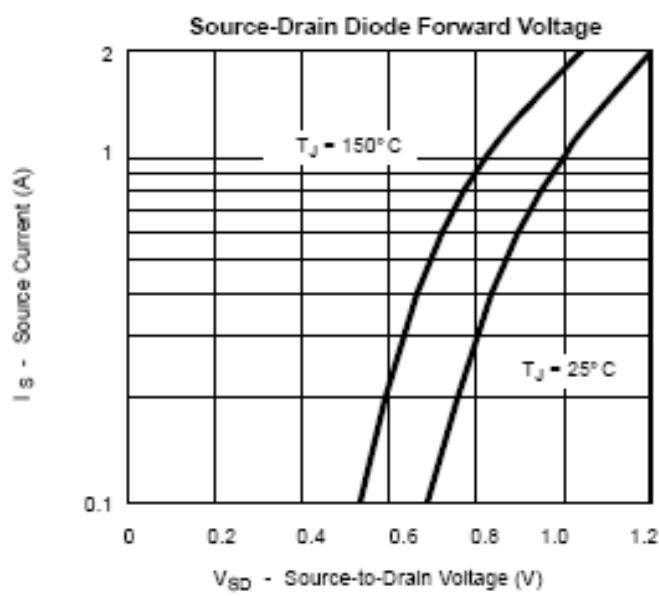
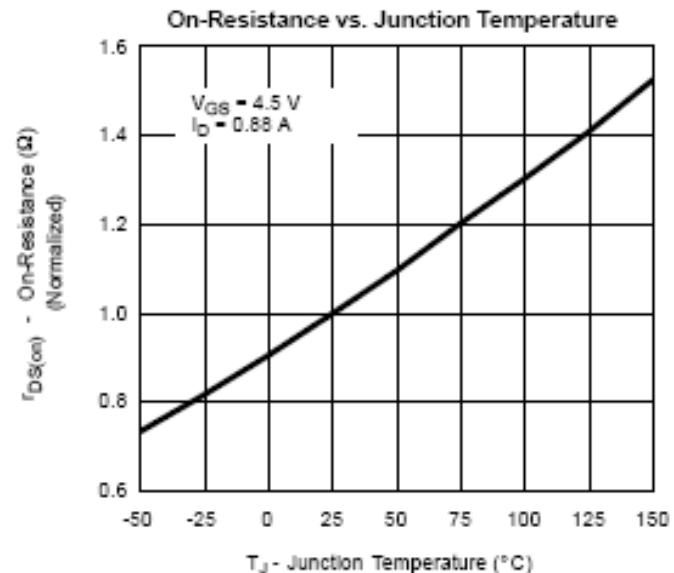
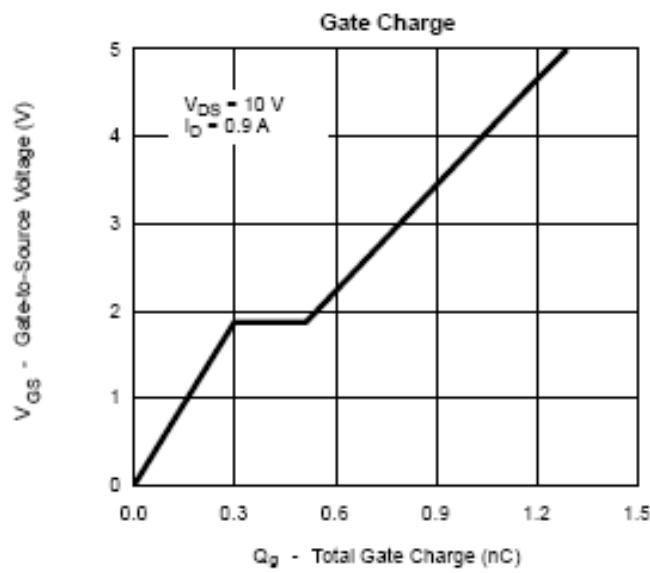




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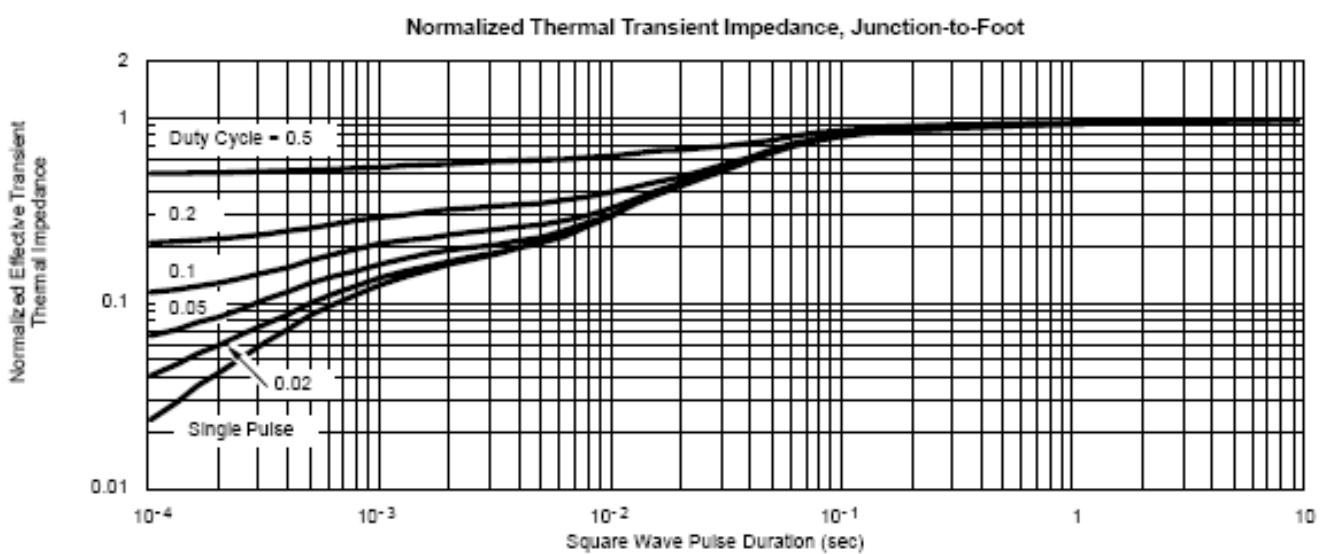
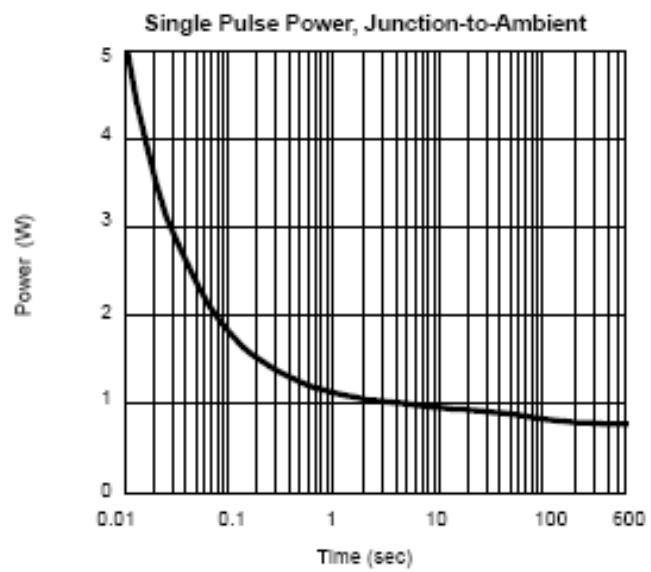
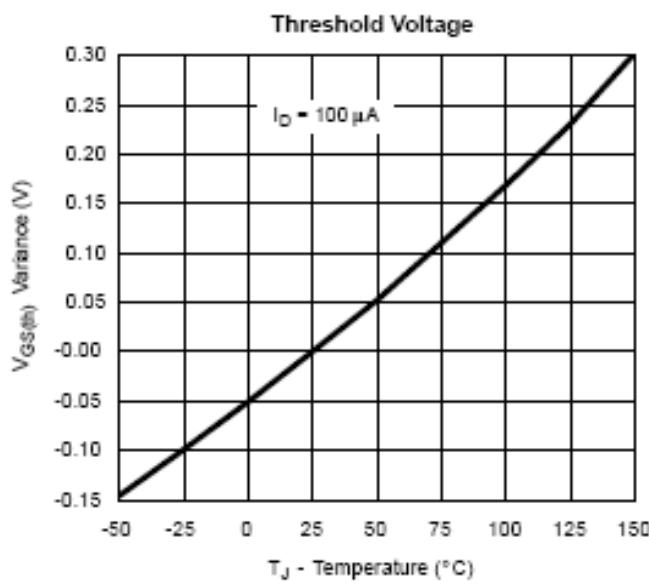




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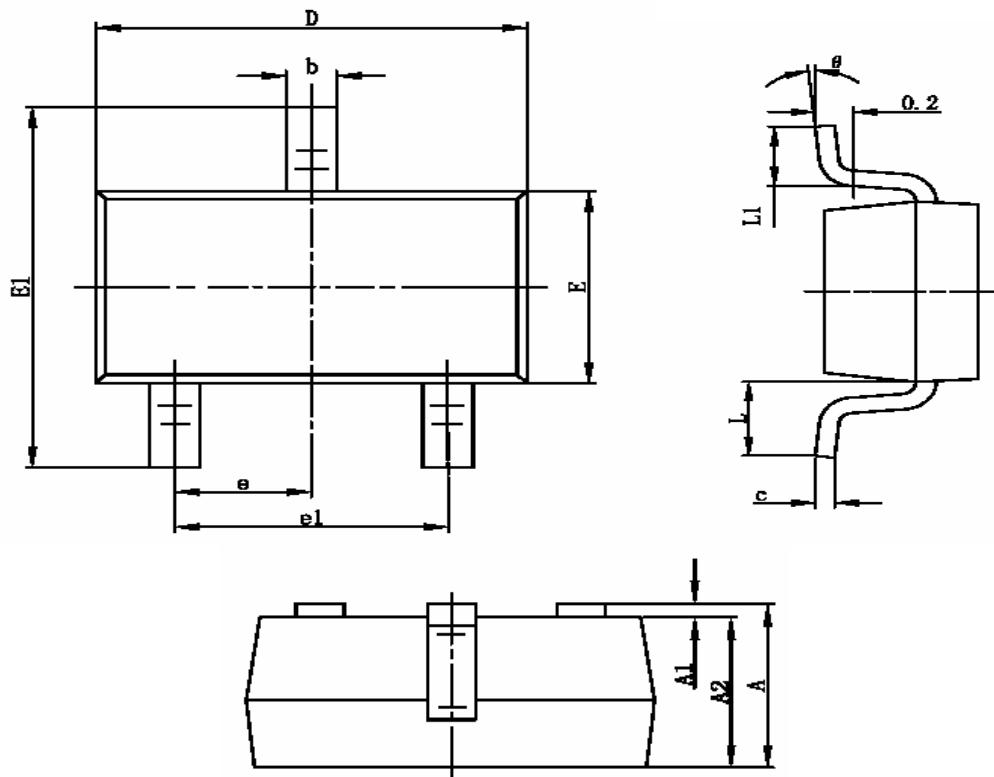




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SOT-23-3L PACKAGE OUTLINE



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.400	0.012	0.016
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.700REF		0.028REF	
L1	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°



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